GND

RESET

TPS3809 ... DBV PACKAGE (TOP VIEW)

2

3

VDD

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- 3-Pin SOT-23 Package
- Supply Current of 9 μA (Typical)
- Precision Supply Voltage Monitor 2.5 V, 3 V, 3.3 V, 5 V
- Power-On Reset Generator With Fixed Delay Time of 200 ms
- Pin-For-Pin Compatible With MAX 809
- Temperature Range . . . –40°C to 85°C

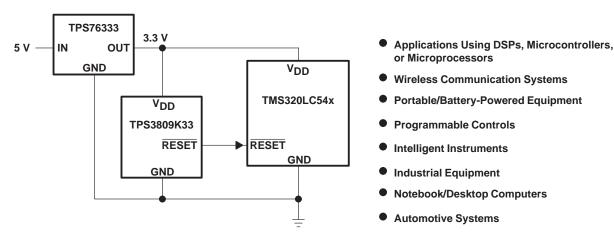
description

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

During power-on, RESET is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps RESET active as long as V_{DD} remains below the threshold voltage V_{IT} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(typ)} = 200$ ms, starts after V_{DD} has risen above the threshold voltage V_{IT} . When the supply voltage drops below the threshold voltage V_{IT} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809 devices are characterized for operation over a temperature range of -40° C to 85° C.

typical applications





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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AVAILABLE OPTIONS									
TA	DEVICE	NAME	THRESHOLD VOLTAGE	MARKING					
	TPS3809J25DBVR [†]	TPS3809J25DBVT‡	2.25 V	PCZI					
–40°C to 85°C	TPS3809L30DBVR [†]	TPS3809L30DBVT [‡]	2.64 V	PDAI					
-40°C 10 85°C	TPS3809K33DBVR [†]	TPS3809K33DBVT [‡]	2.93 V	PDBI					
	TPS3809I50DBVR [†]	TPS3809I50DBVT‡	4.55 V	PDCI					

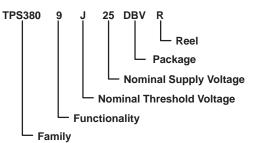
[†] The DBVR passive indicates tape and reel of 3000 parts.

[‡] The DBVT passive indicates tape and reel of 250 parts.

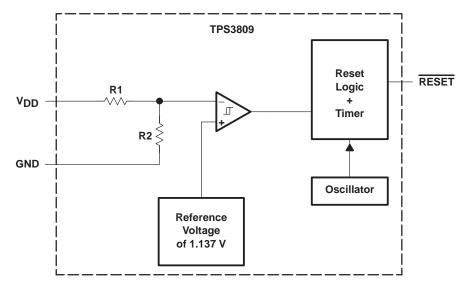
FUNCTION/TRUTH TABLE, TPS3809

V _{DD} >V _{IT}	RESET
0	L
1	н

ORDERING INFORMATION



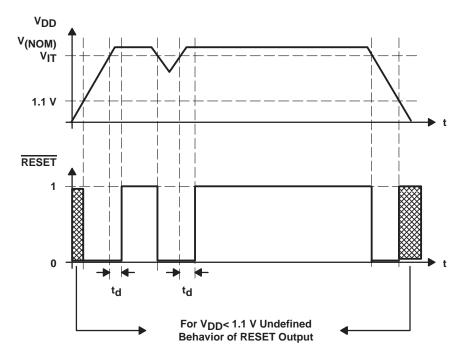
functional block diagram





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timing diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage, V _{DD} (see Note1)	
All other pins (see Note 1)	
Maximum low output current, I _{OL}	5 mA
Maximum high output current, IOH	
Input clamp current, I _{IK} (VI<0 or VI>VDD)	±20 mA
Output clamp current, I _{OK} (V _O <0 or V _O >V _{DD})	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{stg}	
Soldering temperature	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device should not be operated at 7 V for more than t=1000h continuously.

DISSIPATION RATING TABLE								
PACKAGE	T _A <25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING				
DBV	437 mW	3.5 mW/°C	280 mW	227 mW				

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2	6	V
Operating free-air temperature range, T _A	-40	85	°C



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electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					•	•	

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
			V _{DD} = 2.5 V to 6 \	/, I _{OH} = –500 μA	V _{DD} -0.2			
VOH High-level output voltage			V _{DD} = 3.3 V,	I _{OH} = -2 mA	V _{DD} -0.4			V
		V _{DD} = 6 V,	I _{OH} = -4 mA	V _{DD} -0.4				
			$V_{DD} = 2 V \text{ to } 6 V,$	I _{OL} = 500 μA			0.2	
V _{OL} Low-level output voltage		V _{DD} = 3.3 V,	I _{OL} = 2 mA			0.4	V	
				I _{OL} = 4 mA			0.4	
	Power-up reset voltage (see Note a	2)	$V_{DD} \ge 1.1 V$,	I _{OL} = 50 μA			0.2	V
	Negative-going input threshold voltage (see Note 3)	TPS3809J25			2.20	2.25	2.30	
\/. 		TPS3809L30		2.58	2.64	2.70	v	
VIT–		TPS3809K33	T _A – 40°C to 85°C		2.87	2.93	2.99	v
		TPS3809I50			4.45	4.55	4.65	
		TPS3809J25				30		
M .	Hyptorogia	TPS3809L30]			35		mV
V _{hys}	Hysteresis	TPS3809K33]			40		mv
		TPS3809I50				60		
	Currentu current		V _{DD} = 2 V, Outpu	ut unconnected		9	12	
IDD	Supply current	V _{DD} = 6 V, Outpu	ut unconnected		20	25	μA	
Ci	Input capacitance		$V_I = 0 V \text{ to } V_{DD}$			5		pF

NOTES: 2. The lowest supply voltage at which $\overrightarrow{\text{RESET}}$ becomes active. $t_{r, VDD} \ge 15 \,\mu\text{s/V}$. 3. To ensure best stability of the threshold voltage, a bypass capacitor ($0.1 \,\mu\text{F}$ ceramic) should be placed near the supply terminals.

timing requirements at R_L = 1 M\Omega, C_L = 50 pF, T_A = 25°C

		PARAMETER		TEST CONDITIONS			TYP	MAX	UNIT
t	w I	Pulse width	at V _{DD}	$V_{DD} = V_{IT-} + 0.2 V,$	$V_{DD} = V_{IT-} - 0.2 V$	3			μs

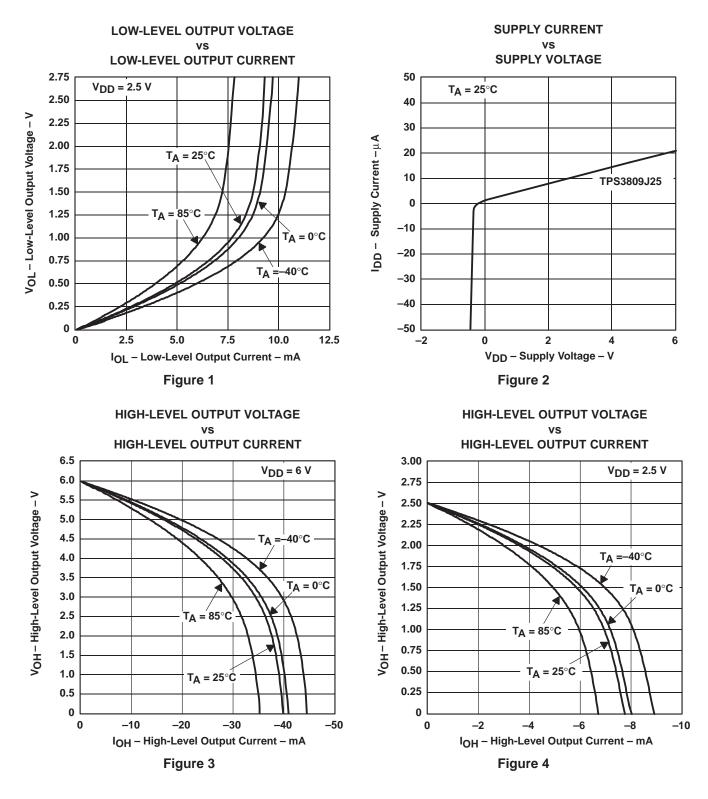
switching characteristics at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
td	Delay time		$V_{DD} \ge V_{IT-} + 0.2 V$, See timing diagram	120	200	280	ms
^t PHL	Propagation (delay) time, high-to-low-level output	V _{DD} to RESET delay	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$		1		μs



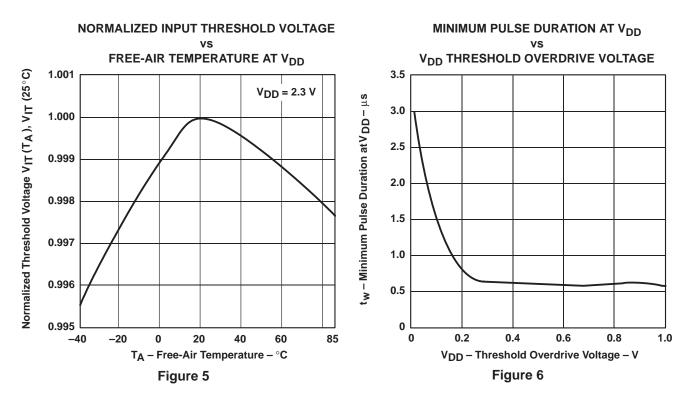
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TYPICAL CHARACTERISTICS





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TYPICAL CHARACTERISTICS

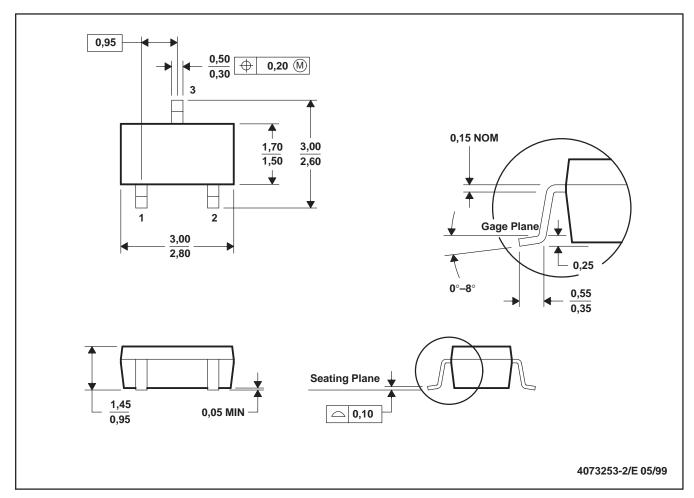


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MECHANICAL DATA

PLASTIC SMALL-OUTLINE

DBV (R-PDSO-G3)



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.



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